

MT18SD-H

- MicroThin為附18 μ m載體銅箔的超薄銅箔。
MicroThin is ultra thin foil with 18 μ m carrier foil.
- 最適用於線寬/線距(L/ S) = 35/35~40/40之應用。
Usable for fine pitch pattern L/S = 35/35 - 40/40 formation.

用途/Application

- IC封裝載板
/Semiconductor Package
- 高密度互連技術板
/High Density Interconnect

構成/Composition



生產地點/Production Site

- 日本 / Japan
- 馬來西亞/Malaysia

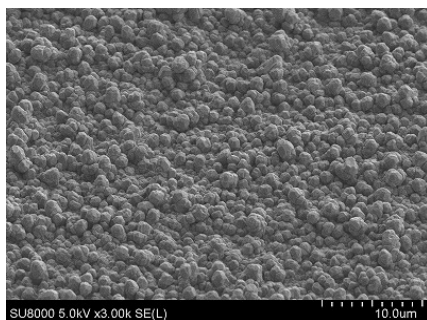
代表性特性數據/Representive

	μ m	Area weight (g/m ²)	Laminate side Rz(μ m)	Tensile Strength (N/mm ²)	Elogation (%)	Peel Strength (kg/cm)@FR-4
MT18SD-H	3	39	3	-	-	1.4
	5	57	3	-	-	1.4

※上述表列為代表性數據非保證值
This is representative data, not guaranteed.

※Peel Strength為增鍍到35 μ m厚度之後的測試值
Evaluated after plated up to 35 μ m.

處理面/Laminate side



阻劑面/ resist side

